



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-09-18
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SMTPA120	8HZG*CW8120M	A	BOUSKOURA B/E	2015-09-18
Amount		UoM	Unit type	ST ECOPACK Grade
98.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SOJ	4.2, 3.7, 2.37	2	J BEND	
Comment	SMB CLIP (SOD 6)			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8HZG*CWB120M					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	0.902	mg	supplier	die	Silicon (Si)	7440-21-3		0.878	mg	973422	8969
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	4430	41
				supplier	Passivation	Silicon Oxide	7631-86-9		0.005	mg	5537	51
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.005	mg		
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	2215	20
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.008	mg	8859	82
Leadframe	Copper & its alloys	40.676	mg	supplier	alloy	Copper (Cu)	7440-50-8		40.623	mg	998697	414520
				supplier	alloy	Iron (Fe)	7439-89-6		0.041	mg	1008	418
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.012	mg	295	122
Soft solder	Solder	1.216	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.137	mg	935033	11602
				supplier	solder	Tin (Sn)	7440-31-5		0.061	mg	50164	622
				supplier	solder	Silver (Ag)	7440-22-4		0.018	mg	14803	184
Encapsulation	Other Organic Materials	36.065	mg	supplier	mold compound	Silica, vitreous	60676-86-0		27.409	mg	759989	279684
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		3.679	mg	102010	37541
				supplier	mold compound	Phenol resin	9003-35-4		2.164	mg	60003	22082
				supplier	mold compound	Others	Proprietary		1.803	mg	49993	18398
				supplier	mold compound	Metal hydroxide	21645-51-2		0.721	mg	19992	7357
				supplier	mold compound	Carbon black	1333-86-4		0.289	mg	8013	2949
Connections coating	Solder	0.811	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.811	mg	1000000	8276
Clip	Copper & its alloys	18.330	mg	supplier	alloy	Copper (Cu)	7440-50-8		18.330	mg	1000000	187041